

Title (en)
COMPONENT USED IN MICROPROCESS CONTROL

Title (de)
MIKROVERFAHRENSCHNISCHER BAUSTEIN

Title (fr)
MODULE MICROMINIATURISE

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Application
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Abstract (en)
[origin: WO2004098768A1] The invention relates to a component used in microprocess control that comprises at least one process control microfluidic element (4) and microfluidic channel connections (9) and that is provided with a thermally insulating housing (1) surrounding the microfluidic element (4). The microfluidic channel connections (9) are guided through the housing (1). Linking elements for linking individual housings (1) are disposed on the housing (1) in such a manner that the respectively assigned microfluidic channel connections (9) can be sealingly interlinked. The microfluidic element (4) is interposed between a connection block (3) and a heat transfer block (2), and the temperature of the heat transfer block (2) and the connection block (3) and thus of the microfluidic element (4) can be controlled. A linking element for interlinking individual housings (1) has a conical screw (21) with a threaded section (22) and a conically tapered section (23). A locking pin (18) with a bore (19) adapted to the conical screw (21) and projecting from a first of the housings (1) to be interlinked is introduced into a recess (20) of a second housing (1) which recess is adapted to the locking pin (18). The locking pin is tightly pressed into said recess by means of the conical screw (21) whose conically tapered section (23) is engaged with the bore (19) of the locking pin (18).

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